



US00D612344S

(12) **United States Design Patent**
Wei et al.

(10) **Patent No.:** **US D612,344 S**
(45) **Date of Patent:** **** Mar. 23, 2010**

(54) **HEAT DISSIPATION DEVICE**
(75) Inventors: **An-Chi Wei**, Miao-Li Hsien (TW);
Shan-Ju Lin, Miao-Li Hsien (TW)
(73) Assignee: **Foxsemicon Integrated Technology, Inc.**, Chu-Nan, Miao-Li Hsien (TW)

6,735,864 B2 * 5/2004 Sato et al. 29/890.03
6,899,164 B1 * 5/2005 Li et al. 165/80.3
7,152,666 B2 * 12/2006 Chen et al. 165/80.3
D581,376 S * 11/2008 Shaner D13/179
7,509,995 B2 * 3/2009 Bhatti et al. 165/80.3
2003/0070790 A1 * 4/2003 Chen et al. 165/80.3
2009/0139690 A1 * 6/2009 Maerz et al. 165/80.2

* cited by examiner

(**) Term: **14 Years**
(21) Appl. No.: **29/339,852**
(22) Filed: **Jul. 8, 2009**

Primary Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Raymond J. Chew

(30) **Foreign Application Priority Data**
Jun. 5, 2009 (CN) 2009 3 0305387

(57) **CLAIM**

The ornamental design for a heat dissipation device, as shown.

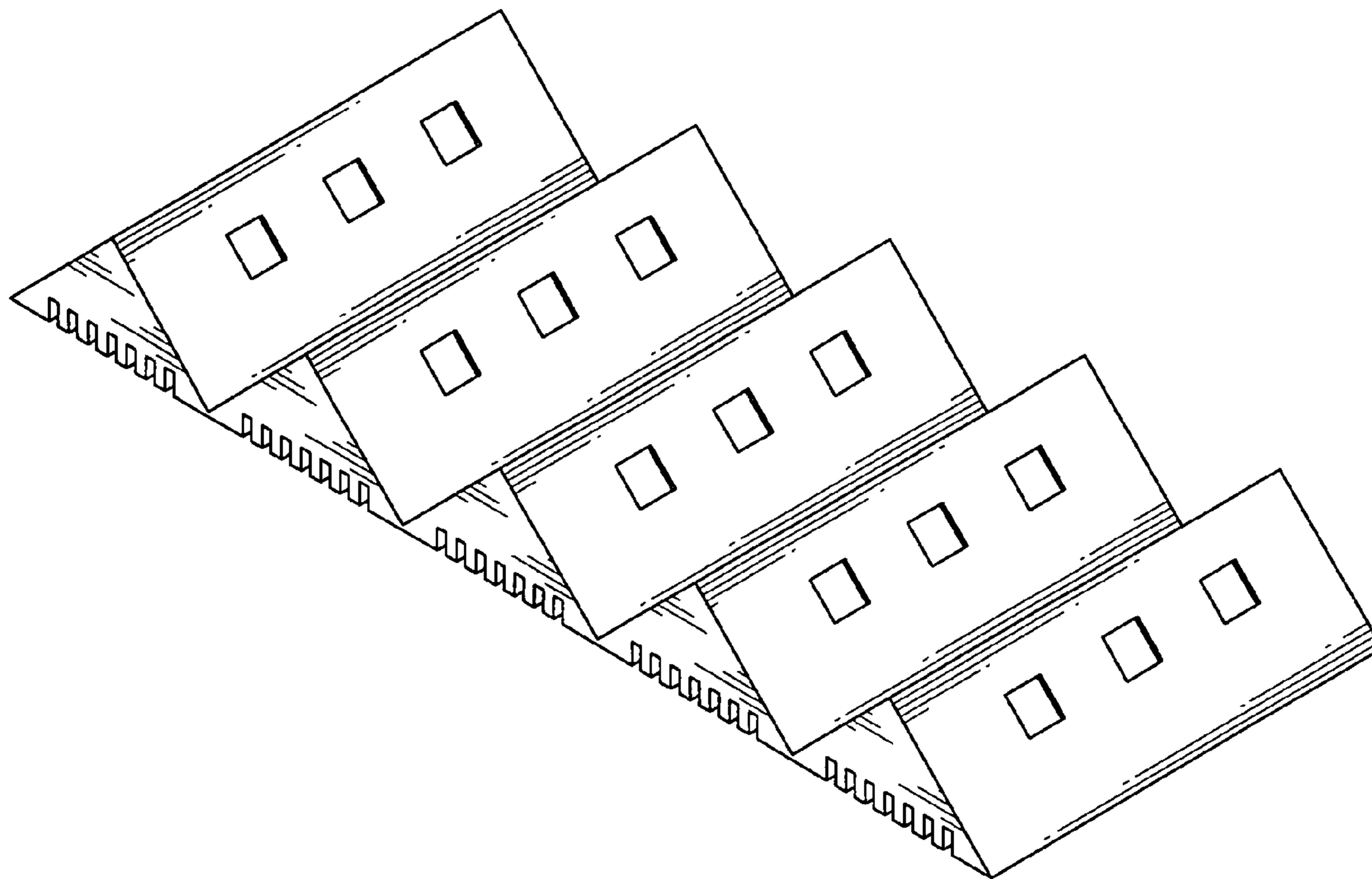
(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/179**
(58) **Field of Classification Search** D13/179;
165/80.3, 104.33, 151, 122, 185; 257/706,
257/707, 718-722; 361/687, 695, 697, 700,
361/702, 704, 709, 710, 711, 719
See application file for complete search history.

DESCRIPTION

FIG. 1 is a perspective view of a heat dissipation device showing our new design.
FIG. 2 is a front elevational view thereof.
FIG. 3 is a rear elevational view thereof.
FIG. 4 is a left-side, elevational view thereof.
FIG. 5 is a right-side, elevational view thereof.
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

(56) **References Cited**
U.S. PATENT DOCUMENTS
6,637,502 B1 * 10/2003 North et al. 165/80.3

1 Claim, 7 Drawing Sheets



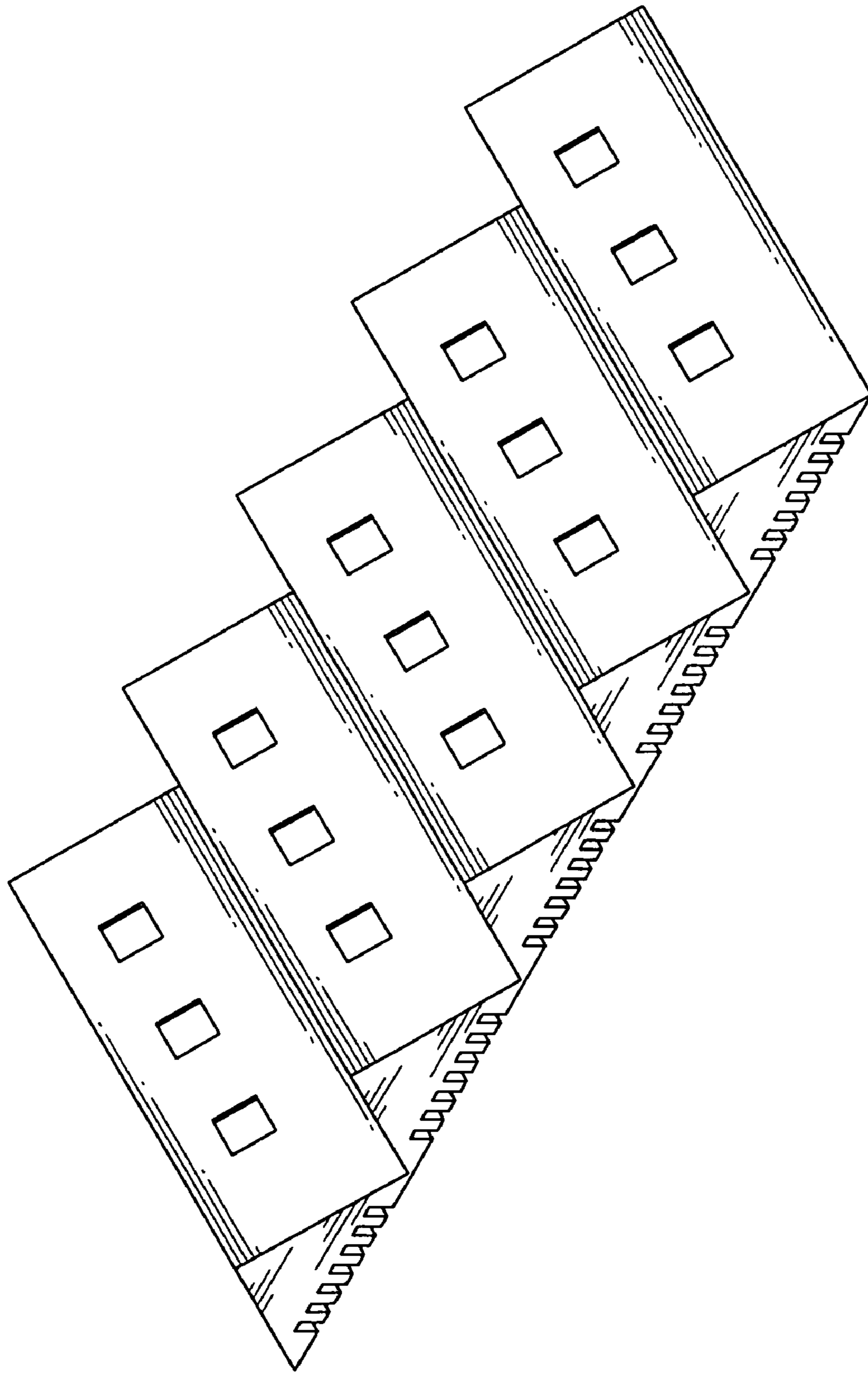


FIG. 1

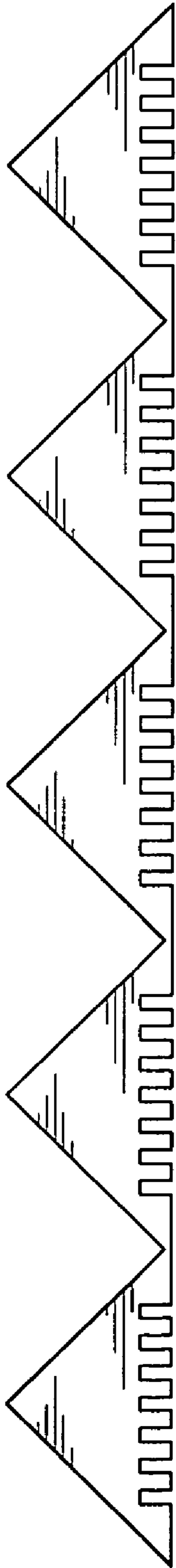


FIG. 2

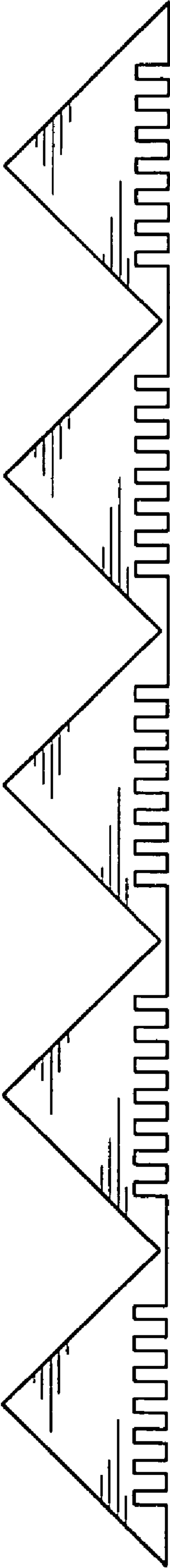


FIG. 3

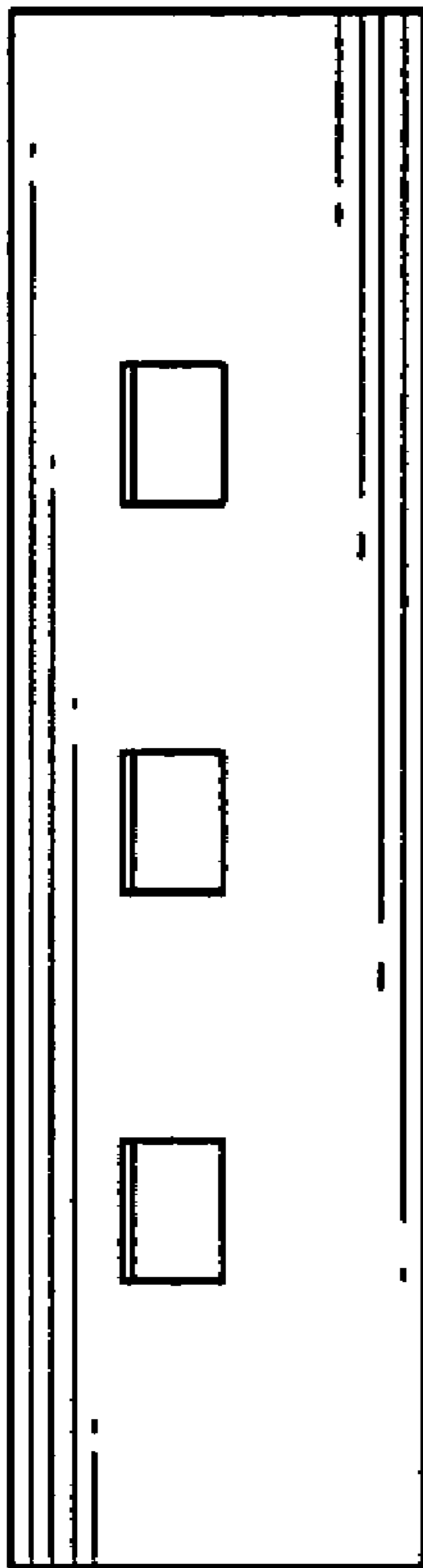


FIG. 4

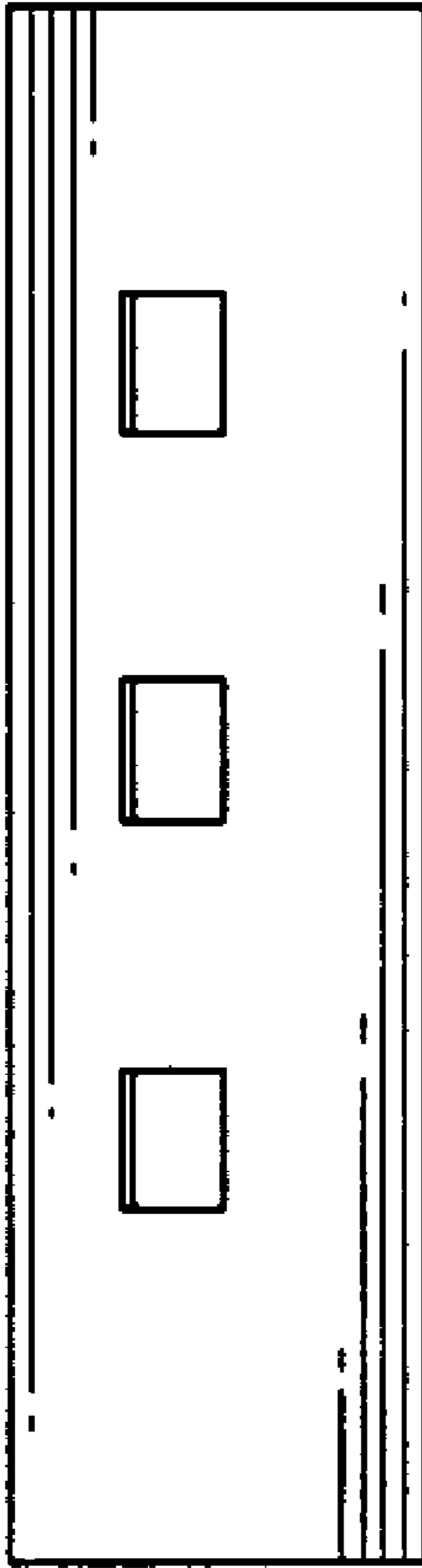


FIG. 5

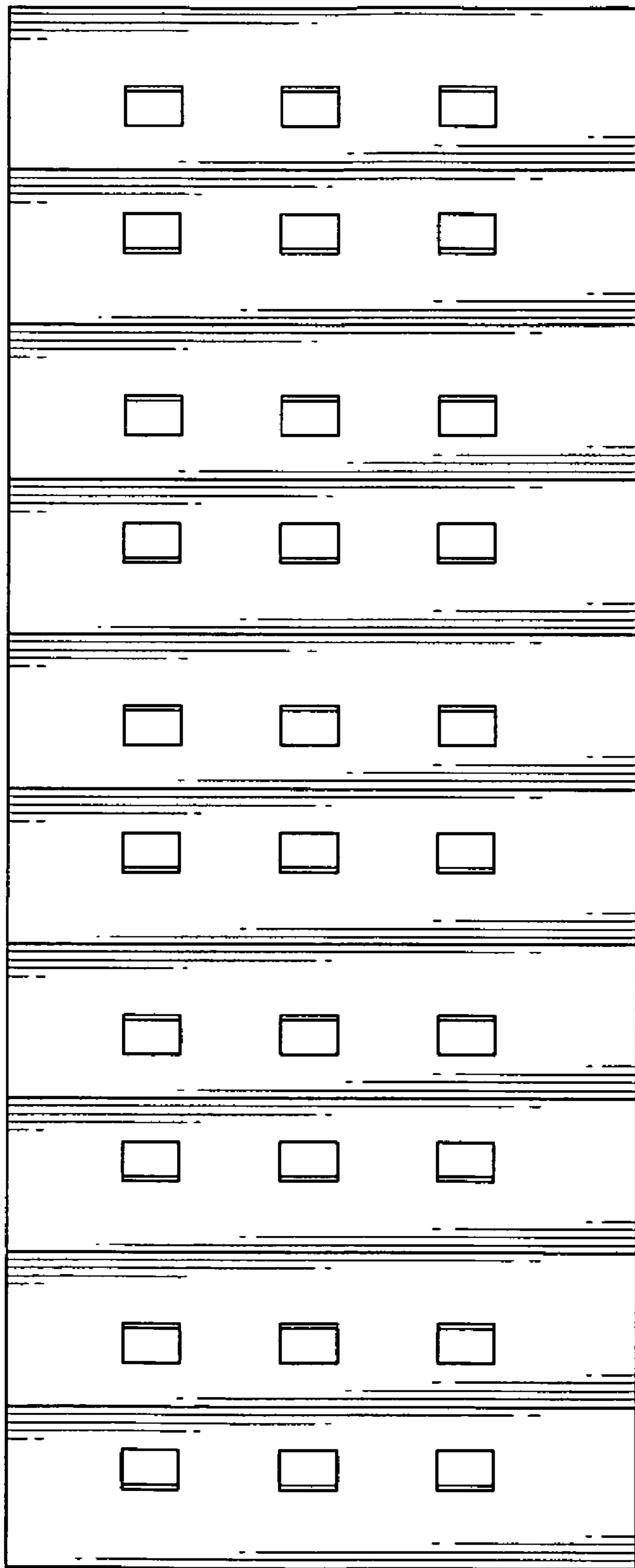


FIG. 6

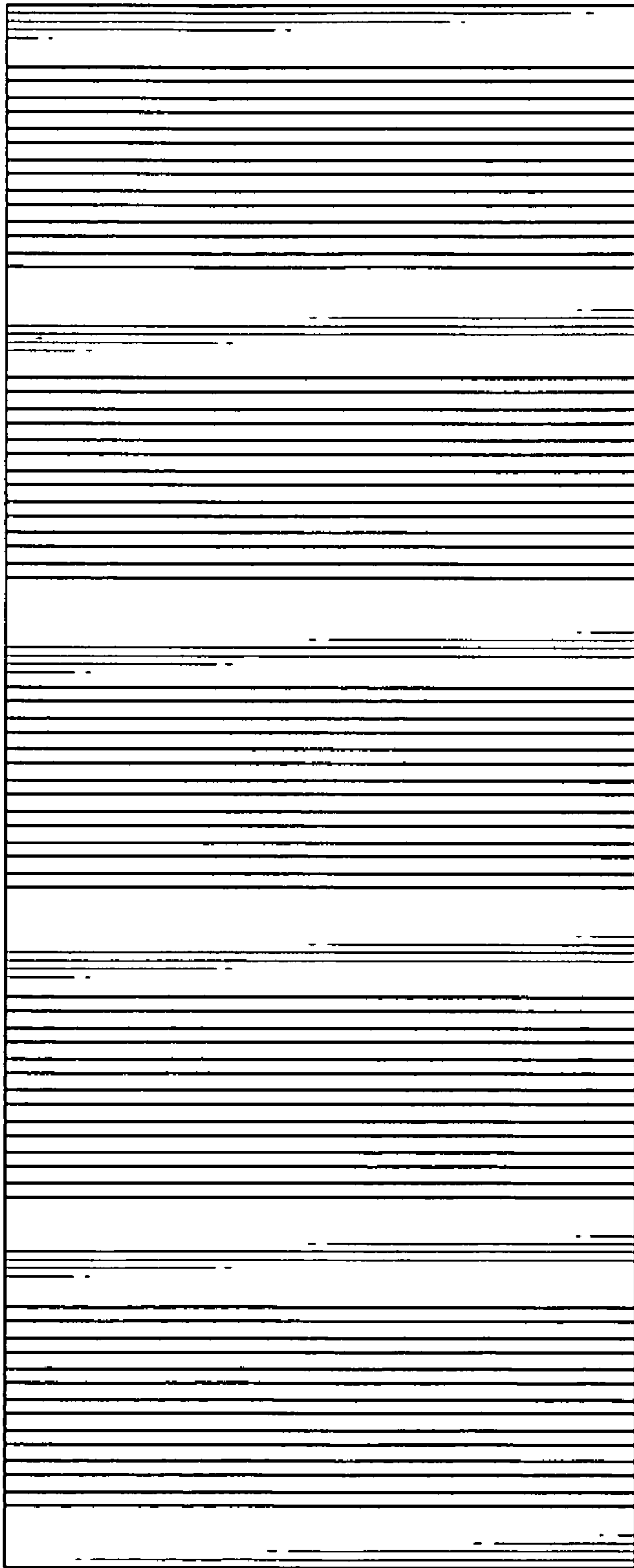


FIG. 7